

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Claims 1, ⁴~~6~~ (canceled).

C1
Claim 5. (currently amended) A chip device comprising:
a leadframe including source and gate connections;
a bumped die including solder bumps on a top side, the bumped die being
attached to the leadframe such that the solder bumps contact the source and gate connections;
and

a copper clip attached to a backside of the bumped die such that the ~~copper~~
copper clip contacts couples drain regions of the bumped die and a lead rail.

Claim 6. (original) A chip device in accordance with claim 5 wherein the copper
clip is attached to the bumped die with solder paste.

Claim 7. (new) A chip device of claim 5 wherein the lead rail has a v-groove.

Claim 8. (new) A chip device of claim 5 wherein the bumped die comprises an
under bump material.

Claim 9. (new) A chip device of claim 5 wherein the lead frame and the lead rail
comprise copper.
